



H-1013

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

T. ISHIDA et al

Serial No. 09/964,484

Examiner: A. Williams

Filed: September 28, 2001

Group Art Unit: 2826

For: A SEMICONDUCTOR DEVICE HAVING STACKED SEMICONDUCTOR
CHIPS SEALED WITH A RESIN SEAL MEMBER (As Amended)

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RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed March 15, 2004, please amend the above-identified application as follows. A Petition and fee for a one-month Extension of Time accompanies this response.

REMARKS

Claims 1-31 are currently pending in the application.

35 USC §103

Claims 1-31 stand rejected under 35 USC 103(a) as being unpatentable over Ohie (U.S. Patent No. 6,580,164) in view of Loder et al (U.S. Patent No. 5,777,345). These rejections are traversed as follows.